

3.2mmx1.6mm SMD CHIP LED LAMP

Features

- 3.2mmx1.6mm SMT LED, 1.1mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- ullet Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- \bullet RoHS compliant.

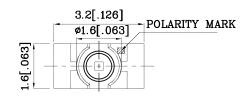




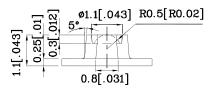
Notes:

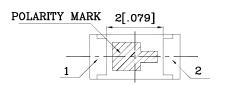
- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)	FBB (InGaN)	Unit		
Reverse Voltage	VR	5	V	
Forward Current	IF	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	100	mA	
Power Dissipation	PD	120	mW	
Operating Temperature	TA	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		









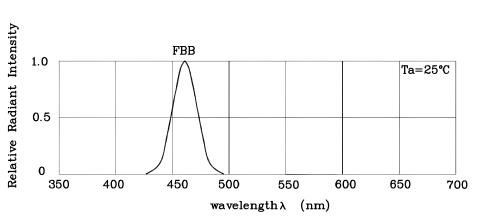
Operating Characteristi (TA=25°C)	FBB (InGaN)	Unit	
Forward Voltage (Typ.) (IF=20mA)	V_{F}	3.3	V
Forward Voltage (Max.) (IF=20mA)	VF	4.0	V
Reverse Current (Max.) (VR=5V)	IR	50	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	465	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	22	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	100	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 0 1/2
				min.	typ.		
XZFBB55W-A2	Blue	InGaN	Water Clear	280	447	465	70°

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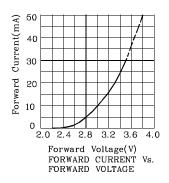


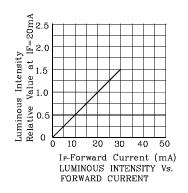
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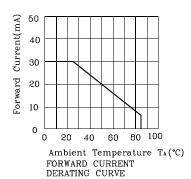


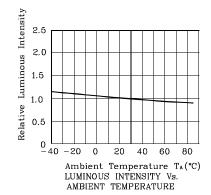
RELATIVE INTENSITY Vs. WAVELENGTH

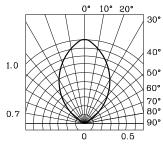
❖ FBB











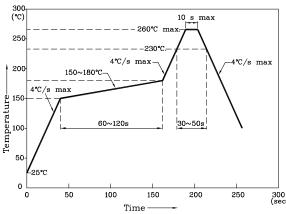
SPATIAL DISTRIBUTION

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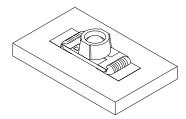
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

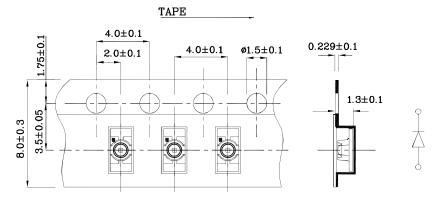


NOTES:

- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: 145°c-260°c.
- Do not put stress to the epoxy resin during high temperatures conditions.
- ❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)
 - 08 1.60
- ❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity/ luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity/ Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

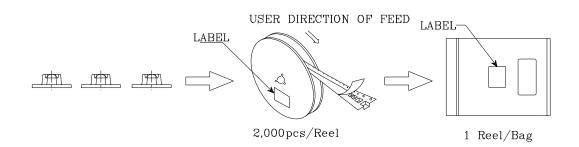
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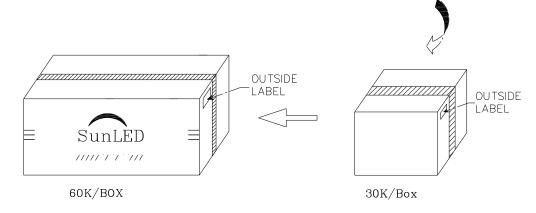


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PACKING & LABEL SPECIFICATIONS

XZFBB55W-A2







P/NO : XZxx55x-A2

QTY: 2,000 pcs

CODE: XXX

S/N : XX

LOT NO:



RoHS Compliant

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